

Metal foil-contg. laminate sheet - has adhesive layer contg. fine inorganic powder and is used for e.g. PCB mfr.

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Abstract (Basic): JP 57045054 A

In a metal foil laminated sheet, the adhesive layer joining the metal foil with the substrate, has fine powder of inorganic substance mixed and dispersed. Laminated sheet having improved solderability, heat resistance, electrical insulating properties, and heat dissipation properties are provided, which may be used for printed circuit board, etc.

Pref. the inorganic powder is of alumina and/or boron nitride, the substrate is of glass base fabric-epoxy resin, ceramic, anodised Al, metal, etc.; and the metal foil is of Cu, Ag, Au, etc. and is 50 micron thick. The adhesive may be of thermosetting epoxy, silicone, polyamide, or imide type.

Title Terms: METAL; FOIL; CONTAIN; LAMINATE; SHEET; ADHESIVE; LAYER;

CONTAIN; FINE; INORGANIC; POWDER; PCB; MANUFACTURE

Index Terms/Additional Words: PRINT; CIRCUIT; BOARD

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